

(12)

United States Design Patent

Yamaji et al.

(10)

Patent No.:

US D1,054,389 S

(45)

Date of Patent:

** Dec. 17, 2024

(54) SEMICONDUCTOR DEVICE

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(73) Assignee: NEC Corporation, Toyko (JP)

(**) Term: 15 Years

(21) Appl. No.: 29/845,090

(22) Filed: Jul. 5, 2022

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(30) Foreign Application Priority Data

Jan. 5, 2022 (JP) 2022-000079 D

(51) LOC (14) Cl. 13-03

(52) U.S. Cl.
USPC D13/182

(58) Field of Classification Search
USPC D13/110, 118, 123, 133, 146, 147, 149,
D13/154, 173, 175, 182, 184, 199
CPC H01L 23/04; H01L 23/055; H01L 23/24;
H01L 23/48; H01L 23/552; H01L 25/18;
H01L 25/50; H01R 12/585; H05K 5/00;
H05K 5/02; H05K 7/00; H05K 7/14;
H05K 7/1427; H05K 7/1435
See application file for complete search history.

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(57) CLAIM

The ornamental design for a semiconductor device as shown and described.

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DESCRIPTION

FIG. 1 is a front view of a semiconductor device showing our new design;

FIG. 2 is a rear elevational view thereof;

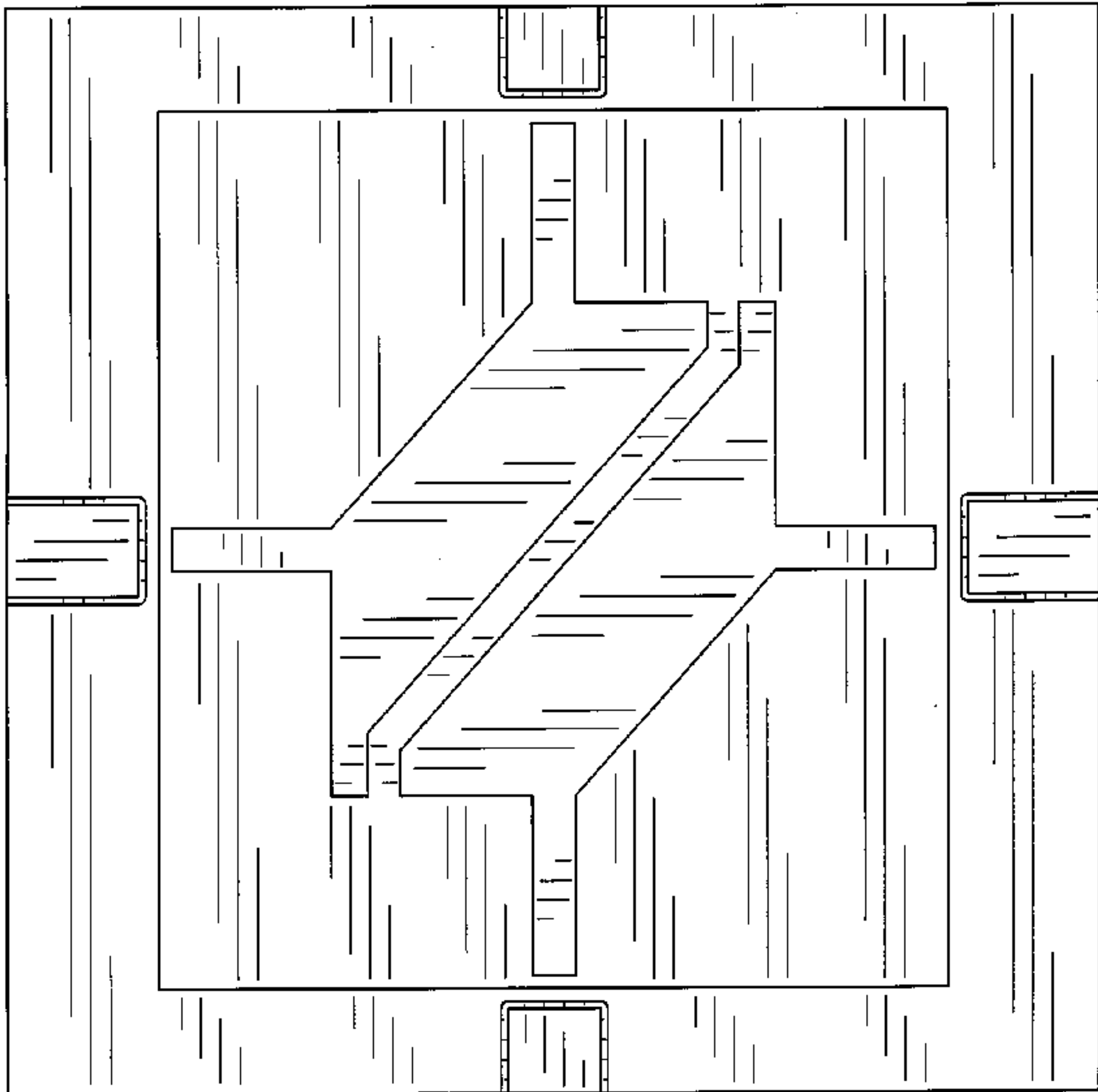
FIG. 3 is a left side view thereof;

FIG. 4 is a right side view thereof;

FIG. 5 is a top plan view thereof; and,

FIG. 6 is a bottom plan view thereof.

1 Claim, 5 Drawing Sheets



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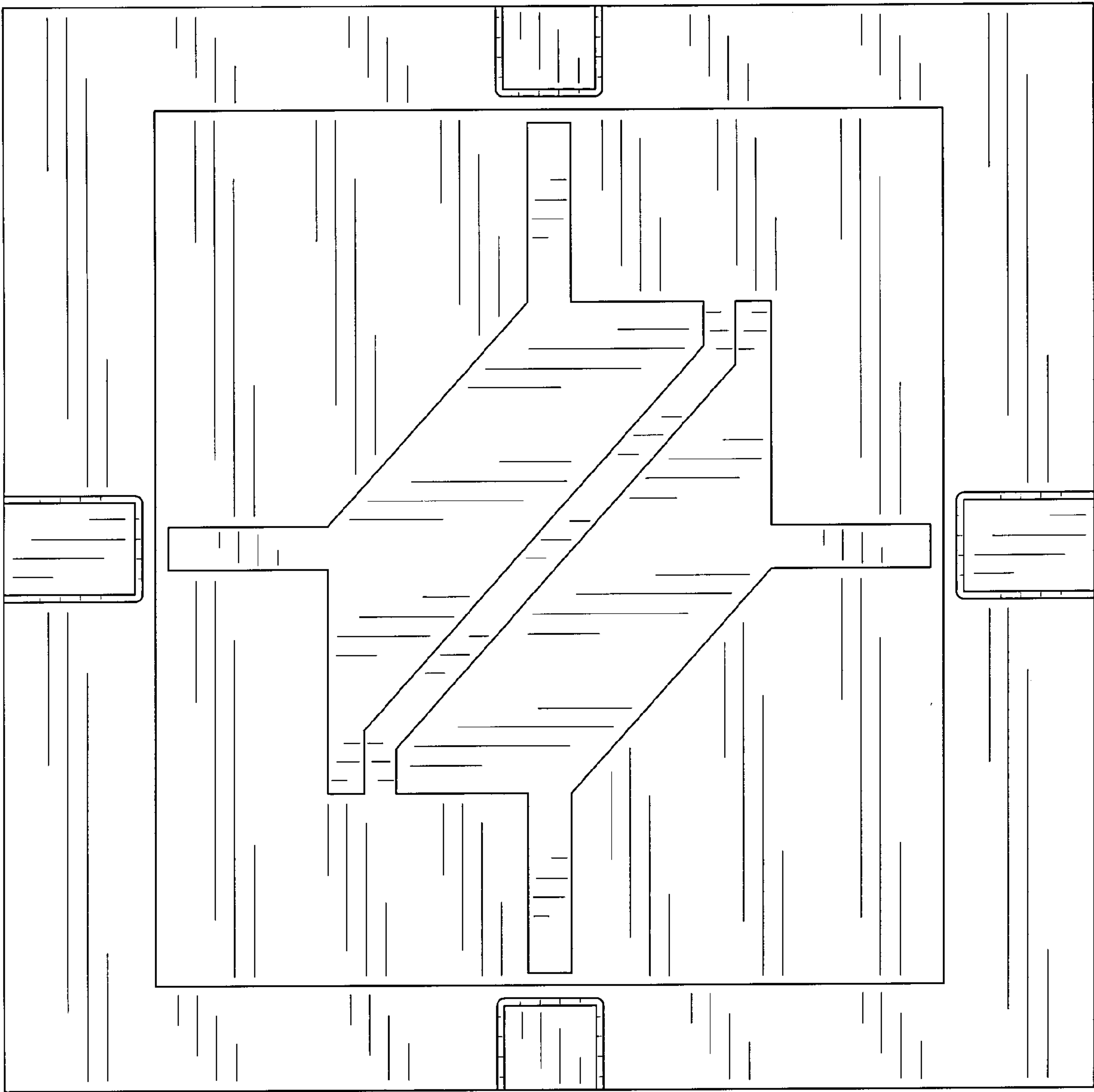


FIG. 1

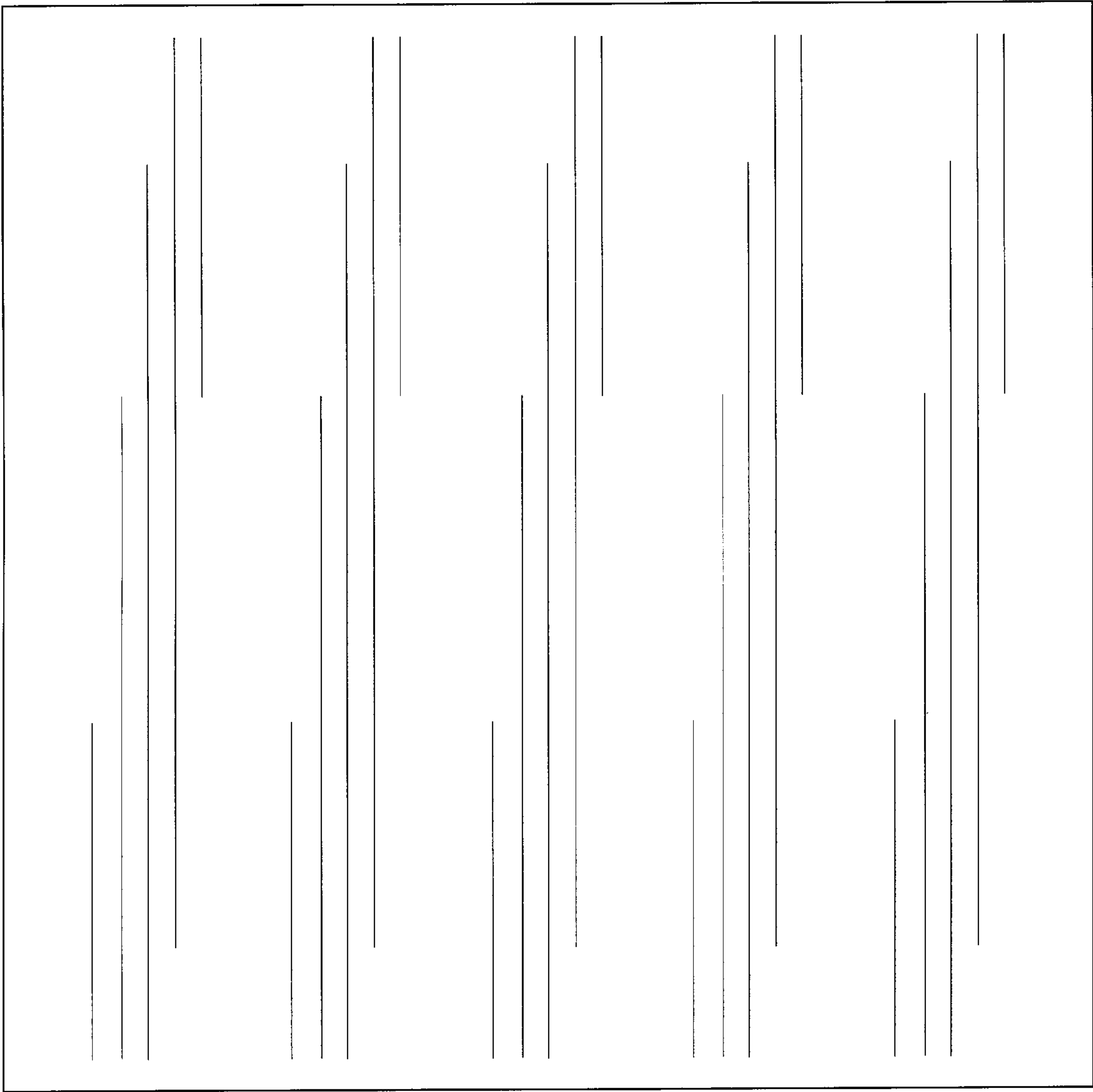


FIG. 2



FIG. 3



FIG. 4



FIG. 5

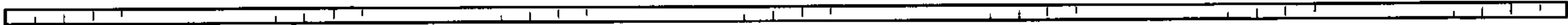


FIG. 6